

Conference News....

2010 INTERNATIONAL CONFERENCE ON ELECTRONIC PACKAGING AND HIGH DENSITY PACKAGING

Xi'an, China

August 16 – 19, 2010

The 11th International Conference on Electronic Packaging Technology & High Density Packaging (ICEPT-HDP) was held in Xi'an, China, from August 16 to 19, 2010. The 11th ICEPT-HDP was organized by the Electronic Manufacturing and Packaging Technology Society of the Chinese Institute of Electronics (CIE-EMPT), and supported by IEEE CPMT. The ICEPT-HDP 2010 was hosted and co-organized by Xidian University. Professor Keyun Bi (Vice Director General of Standing Committee of Chinese Institute of Electronics (CIE); President of Electronic Manufacturing and Packaging Technology Society (EMPT)) served as the General Chair, assisted by five Co-Chairs: Yingtang Tang (Vice President of Xidian University), Rolf Aschenbrenner (President IEEE-CPMT, IZM, Fraunhofer, Germany); William Chen (former President of IEEE-CPMT and Senior Advisor of ASE, USA); Kouchi Zhang (Senior Director and Fellow of Philips Lighting, Professor of Delft University of Technology, Netherlands); and Joahan Liu (Professor of Shanghai University, China, Member of the Royal Swedish Academy of Engineering, Sweden). Dr. Xuejun Fan (Lamar University) serves as Technical Chair.

ICEPT-HDP 2010 was an exciting 4-day event, featuring an Executive Wafer Level Packaging Forum, four professional development courses, 17 plenary keynote presentations, 30 technical oral sessions and three poster sessions, a CPMT workshop, a special session on solid state lighting integration and

reliability, technical exhibition, and many social and networking activities. These venues covered the latest technological developments in electronic packaging, manufacturing and packaging equipment, and provided opportunities to explore the trends of research and development, as well as business in China. There were more than 400 people in attendance, and was the largest in paper submission and attendance in ICEPT history.

The Wafer Level Packaging (WLP) Executive Forum was one of many highlights of this conference. Wafer Level Chip Scale Packaging (WLCSP) is the most prominent WLP product today. Industry analysis report indicates that inside the top three

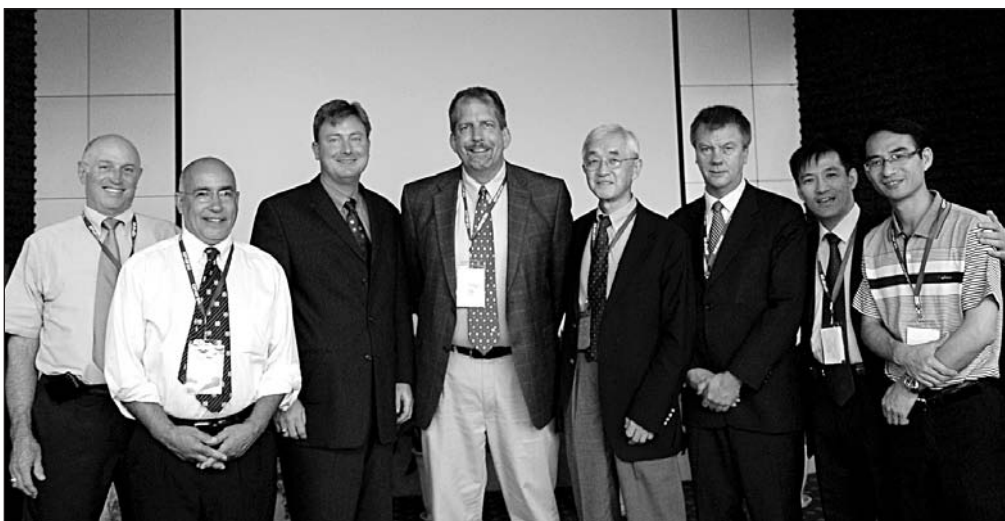


Gathering at Conference Banquet.



Prof. Bi (General Chair) with Rolf Aschenbrenner and William Chen.

high-end smart phones, thirty to fifty percent of the components are WLCSPs. New generations of CMOS Image Sensors (CIS) manufactured in wafer level TSV process, are now implemented in cell phones and other mobile products. The most recent wafer level packaging product in high volume production is the fan-out WLCSP. Wafer level MEMs is positioned for a variety of market implementation. The basic technologies and manufacturing infrastructure (fan-in, fan-out, TSV, MEMs, CIS) are expected to serve as building blocks for heterogeneous and 3D integration, and 3D IC architectures for the global market. The WLP Executive Forum invited a group of senior technologists and veteran business executives from around the globe to share their knowledge, experience and vision. The seven speakers are William Chen (on behalf of Bill Bottoms); John Hunt (Engineering Director, ASE Group); Glenn Daves (Packaging Dev Director, Freescale Semiconductor); Bob Forcier (President & CEO, Flip Chip International); Peter Elenius (Consultant, E&G Technology Partners); Jurgen Wolf (Group & Project Manager ASSID, Fraunhofer IZM); and Herb Huang (Director of Specialty Technology Development Semiconductor



WLP Executive Forum Speakers and Forum Chair/Co-Chair.

Manufacturing International Corporation (SMIC), Shanghai). The Forum was co-chaired by Drs. William Chen and Wenhui Zhu (CTO, Tian Shui Hua Tian Technology Co. Ltd, China). Each executive presented their perspective, at a high-level, of this very important technology, the global market, product applications and future directions addressing questions such as “what will be the new markets and product applications?” “How will the technologies evolve? What will be the business models and opportunities?” This forum was sponsored by CPMT, ASE Groups and Tianshui Huatian Technology Co.).

On the opening day of the conference, seventeen distinguished speakers were invited to give keynote presentations. Mr. Rolf Aschenbrenner gave an overview of chip embedding technology for IC packaging. Prof. Zou Shichang of Chinese Academy of Science presented an overview of China’s IC industry after the global financial crisis. Dr. Mark Brillhart presented the packaging challenges and technology innovations in high performance networking products. Prof. Kouchi Zhang brought a new perspective and the new technology landscape in solid state lighting.

Thirty technical oral sessions brought the latest technology developments in in electronic packaging, manufacturing and packaging equipment. Many of the sessions focused on 3D/TSV, new materials and reliability challenges. This year three separate poster sessions, each with more than 60 posters, were arranged in dedicated time slots to promote interactive technical discussions. A total of 15 outstanding papers were awarded from both oral and poster sessions.

CPMT workshop was another highlight of the conference. Drs. Kitty Pearsall (VP of CPMT, Member of the Academy of Technology, IBM), and Ricky Lee (Editor-in-

Chief of TCPT, Professor of HKUST, Hong Kong) hosted and presented in this workshop. The workshop addressed the importance of the IEEE Components, Packaging and Manufacturing Technology (CPMT) Society in building members career. The workshop also included a presentation about best practices for the generation of “high impact” technical papers, including key attributes of “high impact” papers; a list of “must dos” for authors as they prepare their technical paper for submission; the use of communities of interest to determine which Society transaction is the best one to submit paper to for consideration; and a list of resources.

A special session on solid state lighting (SSL) integration and assembly was organized in this conference. A large attendance joined this special session for technical discussions on the latest developments in packaging, assembly and reliability challenges in SSL system. Philips Lighting sponsored this special session for the selection of the Best SSL Integration Paper Awards.

Cisco sponsored the Best Student Paper Awards. A total of six student papers were selected for the award.



Dr. Ricky Lee at CPMT Workshop.



Cisco Best Student Paper Awards Ceremony.